

application has nothing to do with a spacer and therefore reconsideration of the requirement that the spacer be defined in the abstract is respectfully requested.

Claim 15 has been amended to call for wire bonding both of the stacked semiconductor dies to the leadframe. In Ball, only one of the semiconductor dies is wire bonded to the leadframe. Since Ball is assigned to the assignee of the present application, a §103 rejection based on Ball would be unavailing.

New independent claim 32 calls for connecting one of a first and second semiconductor dies to a leadframe and connecting the other die solely to the first semiconductor die and not connecting the second semiconductor die to the leadframe.

In contrast, in Ball, both semiconductor dies are connected directly to the leadframe. Therefore, claim 32 and the claims dependent thereon are in condition for allowance.

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In view of these remarks, the application is now in condition for allowance and the Examiner's prompt action in accordance therewith is respectfully requested.

Respectfully submitted,

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APPENDIX

In the Title:

Please amend the title to read:

“Method of Fabricating Mounted Multiple Semiconductor Dies in a Package”.

In the Claims:

Please amend claim 15 as follows:

15. (Amended) A method for mounting multiple semiconductor dies on a single leadframe, comprising:

stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another; and

[electrically connecting] wire bonding each of the semiconductor dies to the leadframe.

Please amend claim 16 as follows:

16. (Amended) The method of claim 15, wherein [a first] one of said semiconductor [die] dies is mounted back to back on [a second] the other of said semiconductor [die] dies.

Please amend claim 17 as follows:

17. (Amended) The method of claim 16, wherein [the first] one of said semiconductor [die] dies is adhered to [the second] the other of semiconductor [die] dies by an adhesive layer.

Please add the following new claims 32, *et seq.*

32. (New) A method for mounting multiple semiconductor dies on a single leadframe, comprising:

stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of one another;

mounting the first semiconductor die on a leadframe; and

mounting the second semiconductor die only on said first semiconductor die.

33. (New) The method of claim 32 including wire bonding the first and second semiconductor dies to the leadframe.

34. (New) The method of claim 32 wherein the first semiconductor die is mounted back to back on the second semiconductor die.

35. (New) The method of claim 34 wherein the first semiconductor die is adhered to the second semiconductor die by an adhesive layer.